



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents  
Washington, D.C. 20231

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on February 18, 2003

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Harold C. Moore

Name of person mailing document or fee

[Signature]  
Signature

February 18, 2003

Date of Signature

*Entered  
Inclusion  
4/16/03*

Re: Application of: Newell E. Chiesl  
Serial No.: 09/960,441  
Filed: September 21, 2001  
Confirmation No.: 5776  
For: Arrangement for Measuring Pressure on a  
Semiconductor Wafer and an Associated  
Method for Fabricating a Semiconductor  
Wafer  
03/04/2003 ASMITH 00000005 130014 09960441  
01 FC:1201 84.00 CH Group Art Unit: 2812  
02 FC:1202 126.00 CH Examiner: Viktor Simkovic  
Our Docket: 1003-0610

Adjustment date: 07/29/2003 SDIRETA1  
03/04/2003 ASMITH 00000005 130014 09960441  
02 FC:1202 126.00 CR

RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action dated November 18, 2002 for the above-identified  
patent application, please amend the application as follows: